

<b>SPECIFICATION SHEET NO.</b>	S0317 - SDR315M500S012	
<b>ORIGINAL MFG/PART NO.</b>	TGS Crystals/SDR 315.5MA TLF/R315.5S12	
<b>NEXTGEN PART CODE</b>	SDR315M500S012	Indicate This Code For <a href="#">RFQ</a> /Order
<b>DATE</b>	Mar. 17, 2025	
<b>REVISION</b>	A2	Updated With Most Recent Data
<b>DESCRIPTION AND MAIN PARBMETRICS</b>	<p>SMD SAW Resonator, 6 Pads, 3030 Type, SDR Series</p> <p>Dimension L3.0*W3.0*H1.25mm</p> <p>Center Frequency 315.500MHz; Frequency Tolerance <math>\pm 75</math>KHz</p> <p>Insertion Loss: 1.5dB Typical, 2.0dB Max.</p> <p>Operating Temp. Range -40°C ~ +85°C</p> <p>Reflow Profile Condition 260°C Max.</p> <p>Package in Tape/Reel, 3000pcs/Reel</p> <p>REACH/RoHS/RoHS III Compliant</p>	
<b>CUSTOMER</b>		
<b>CUSTOMER PART NUMBER</b>		
<b>CROSS REF. PART NUMBER</b>		
<b>MEMO</b>		

<b>VENDOR APPROVE</b>		
Issued/Checked/Approved		
		
Effective Date: Mar. 17, 2025		

<b>CUSTOMER APPROVE</b>
Date:

## MAIN FEATURE

- SMD SAW Resonator 3030 Type 6 Pads
- Dimension L3.0\*W3.0\*H1.25mm
- Low-loss SAW Resonator
- One Port SAW Resonator
- Ceramic Package For Surface Mounted Technology (SMT)
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level (MSL) 1
- Short Lead time
- Cross Competitors Parts and More
- REACH/RoHS/RoHS III Compliant



*Image shown is a representation only. Exact specifications should be obtained from the product dimension.*



## APPLICATION

- Bluetooth, Wireless Communication Set
- Communication Electronics

## ELECTRICAL CHARBCTERISTICS

- See Page 5
- All Products Parameters are Subject To NextGen Components' Final Confirmation.

### HOW TO ORDER

- Please Follow Up Part Code Guide And Indicate NextGen Part Code SDR315M500S012 For RFQ and Order.

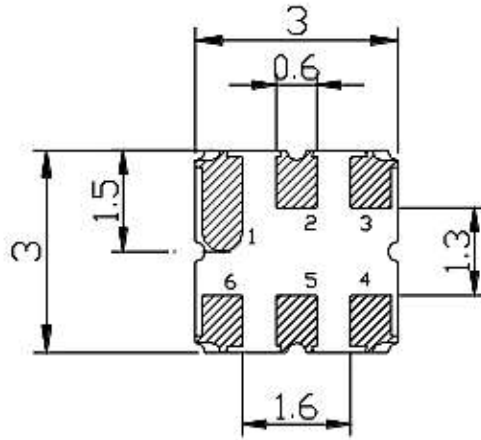
### PART CODE GUIDE

**RFQ**  
[Request For Quotation](#)

CODE	NAME	KEY SPECIFICATION OPTION
SDR	Series Code	SMD SAW Resonator, 6 Pads, 3030 Type Dimension L3.0*W3.0*H1.25mm
315M5	Frequency Range Code	315M5: 315.500MHz
00S012	Internal Control Code	Letter A~Z, a~z or Digits (1-9)
XX	Special/Custom Parameters Code	Blank: N/A XX: Letter A~Z, a~z or Digits (0~9) for Special/Custom Parameters

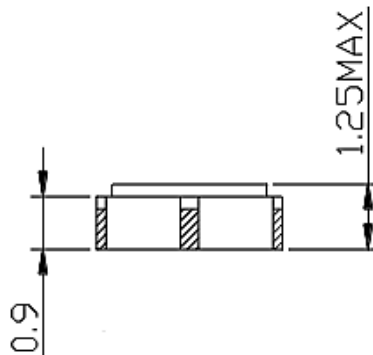
**DIMENSION** - Unit: mm, L3.0\*W3.0\*H1.25mm

Bottom View



PIN	CONFIGURATION
2	Input/Output
5	Output/Input
1, 3, 4, 6	Case Ground

Side View



**MAX. RATING & CHARACTERISTICS** - At 25±2°C Ambient Temperature Unless Otherwise Specified.

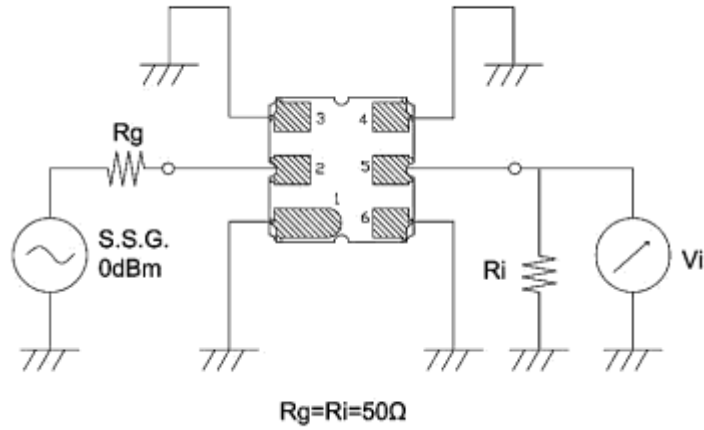
PARAMETER	SYMBOLS	VALUE	UNITS
RF Power Level	P	10	dBm
DC Voltage	V <sub>DC</sub>	±30	V
Operating Temperature Range	T <sub>A</sub>	-40 to +85	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +125	°C

**ELECTRONICAL CHARACTERISTICS**

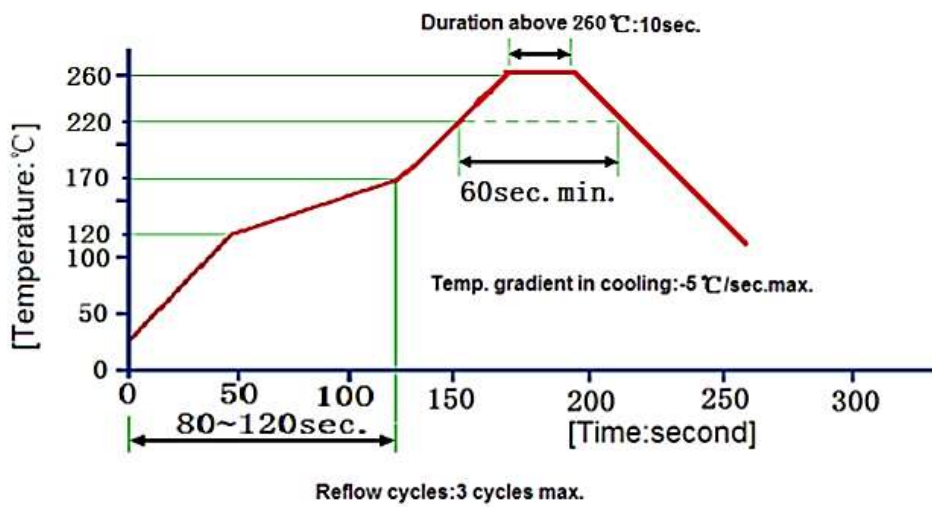
1) Test Temperature: 25°C±2°C 2) Terminating source impedance: 50Ω 3) Terminating load impedance: 50Ω .

PARAMETER		SYMBOLS	CHARACTERISTICS			
			MIN.	TYPICAL	MAX.	UNIT
Center Frequency- Absolute Frequency		F <sub>C</sub>	-	315.500	-	MHz
Frequency Tolerance from 315.500MHz		Δf <sub>c</sub>	-	± 75	-	KHz
Insertion Loss		IL	-	1.5	2.0	dB
Quality	Unloaded Q	Q <sub>U</sub>	-	17396	-	
Factor	50Ω Loaded Q	Q <sub>L</sub>	-	2518	-	
Temperature	Turnover Temperature	T <sub>0</sub>	25	40	55	°C
Stability	Frequency Temp. Coefficient	FTC	-	0.032	-	ppm/°C
Frequency Aging	Absolute Value during the 1 <sup>st</sup> Year	f <sub>A</sub>	-	≤10	-	ppm/yr
DC Insulation Resistance between Any Two Pins			1.0	-	-	MΩ
RF Equivalent RLC Model	Motional Resistance	R <sub>M</sub>	-	16.9	25	Ω
	Motional Inductance	L <sub>M</sub>	-	148.8	-	μH
	Motional Capacitance	C <sub>M</sub>	-	1.72	-	fF
	Static Capacitance	C <sub>0</sub>	2.3	2.6	2.9	pF

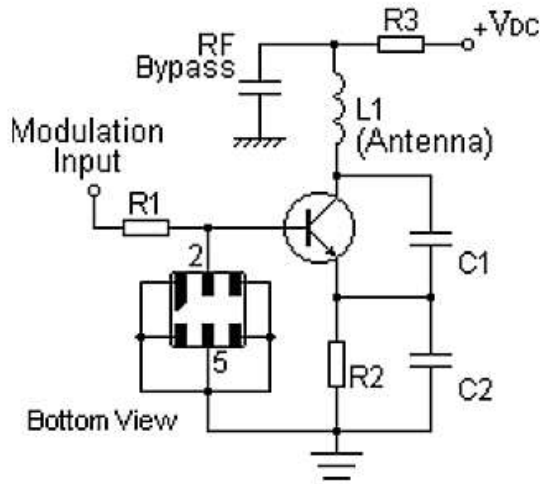
**MEASUREMENT CIRCUIT – FOR REFERENCE ONLY**



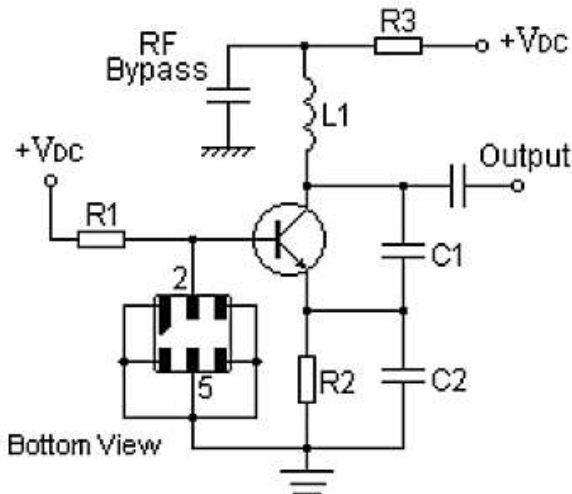
**RECOMMENDED SOLDERING PROFILE – FOR REFERENCE ONLY**



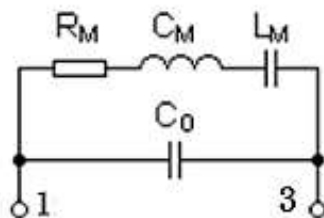
**TYPICAL LOW-POWER TRANSMITTER APPLICATION – FOE REFERENCE ONLY**



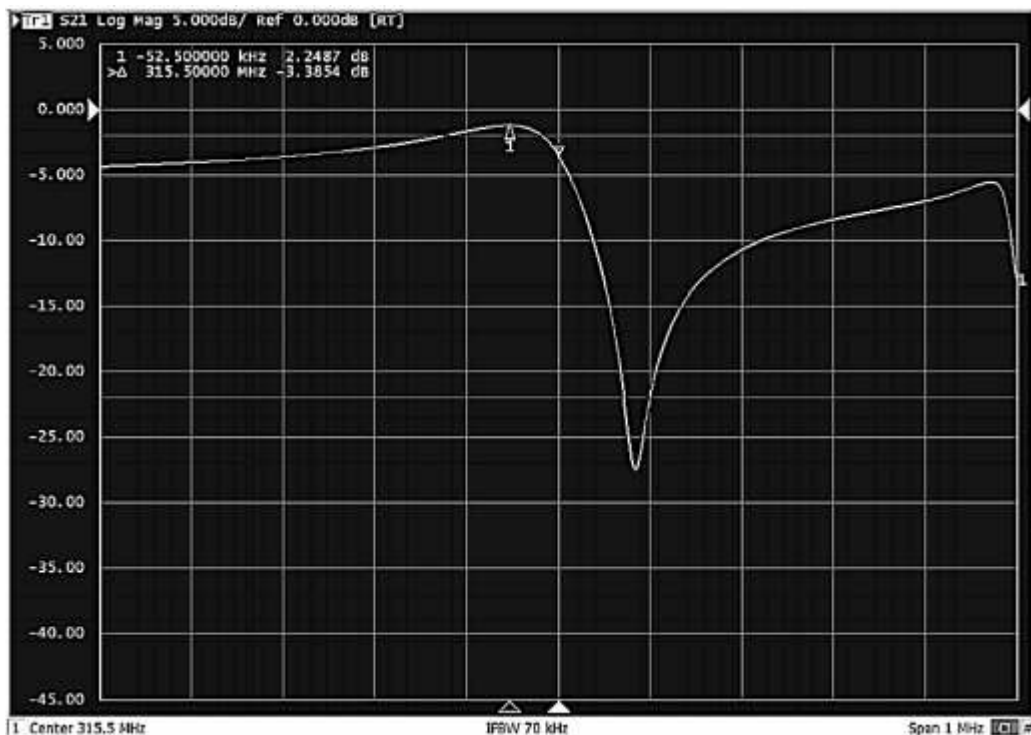
**TYPICAL LOCAL OSCILLATOR APPLICATION – FOE REFERENCE ONLY**



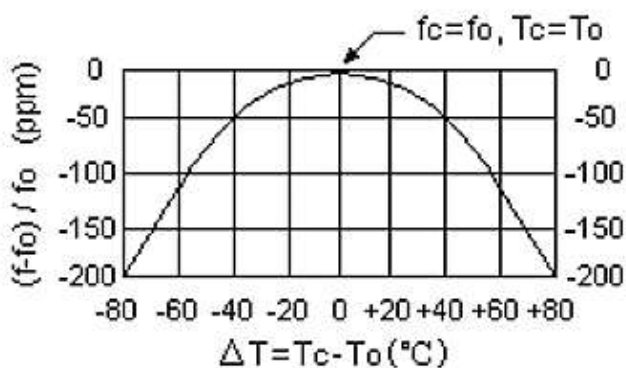
**EQUIVALENT LC MODEL – FOR REFERENCE ONLY**



## FREQUENCY RESPONSE – FOR REFERENCE ONLY



## TEMPERATURE CHARACTERISTICS – FOR REFERENCE ONLY



- Note: The curve shown above accounts for resonator contribution only and does not include LC component temperature contributions.



**RELIABILITY CHARACTERISTICS**

TEST ITEMS	TEST METHOD AND CONDITIONS
Temperature Storage	<ul style="list-style-type: none"> <li>Temperature: <math>85^{\circ}\text{C} \pm 2^{\circ}\text{C}</math>, Duration: 250h , Recovery time: <math>2\text{h} \pm 0.5\text{h}</math></li> <li>Temperature: <math>-40^{\circ}\text{C} \pm 3^{\circ}\text{C}</math>, Duration: 250h ,Recovery time: <math>2\text{h} \pm 0.5\text{h}</math></li> </ul>
Humidity Test	<ul style="list-style-type: none"> <li>Conditions: <math>60^{\circ}\text{C} \pm 2^{\circ}\text{C}</math> , 90~95% RH, Duration: 250h</li> </ul>
Thermal Shock	<ul style="list-style-type: none"> <li>Heat cycle conditions: <math>\text{TA} = -40^{\circ}\text{C} \pm 3^{\circ}\text{C}</math>, <math>\text{TB} = 85^{\circ}\text{C} \pm 2^{\circ}\text{C}</math>, <math>t_1 = t_2 = 30\text{min}</math>,</li> <li>Switch time: <math>\leq 3\text{min}</math>, Cycle time: 100 times,</li> <li>Recovery time: <math>2\text{h} \pm 0.5\text{h}</math>.</li> </ul>
Vibration Fatigue	<ul style="list-style-type: none"> <li>Frequency of vibration: 10~55Hz, Amplitude:1.5mm</li> <li>Directions: X,Y and Z, Duration: 2h</li> </ul>
Drop Test	<ul style="list-style-type: none"> <li>Cycle time: 10 times, Height: 1.0m</li> </ul>
Solderability	<ul style="list-style-type: none"> <li>Temperature: <math>245^{\circ}\text{C} \pm 5^{\circ}\text{C}</math>, Duration: 3.0s--5.0s, Depth: DIP--2/3 , SMD--1/5</li> </ul>
Resistance to Soldering Heat	<ul style="list-style-type: none"> <li>Thickness of PCB:1mm , Solder condition: <math>260^{\circ}\text{C} \pm 5^{\circ}\text{C}</math> , Duration: <math>10 \pm 1\text{s}</math></li> <li>Temperature of Soldering Iron: <math>350^{\circ}\text{C} \pm 10^{\circ}\text{C}</math> , Duration: 3~4s ,</li> <li>Recovery time : <math>2 \pm 0.5\text{h}</math></li> </ul>
Remarks	<ul style="list-style-type: none"> <li>As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.</li> <li>Static voltage between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.</li> <li>Ultrasonic cleaning may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.</li> <li>Only leads of component may be soldered. Please avoid soldering another part of component.</li> <li>There is a close relationship between the device's performance and matching network. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.</li> </ul>



## IMPORTANT NOTES AND DISCLAIMER

1. **ROHS COMPLIANCE:** The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for this product can be obtained at Download Center.
2. **REACH COMPLIANCE:** REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained at Download Center.
3. All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
4. NextGen Component, Inc (*NextGen*) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
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7. *NextGen* products are not authorized for use as critical components in life support devices or systems without express written approval by *NextGen*.
8. *NextGen* requires that customers first obtain an RMA (Returned Merchandise Authorization) number prior to returning any products. Returns must be made within 30 days of the date of invoice, be in the original packaging, unused and like-new condition. At the time of quoting or purchasing, a product may say that it is Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable.